# PROJEK DEVICES

SM16LC03 thru SM16LC36C

## LOW CAPACITANCE TVS ARRAY

#### **APPLICATIONS**

- ✓ Wireless Communication Circuits
- ✔ RS-422, RS-432 & RS-485
- ✓ Low Voltage ASICs
- ✓ Ethernet 10/100 Base T

### IEC COMPATIBILITY (EN61000-4)

- ✓ 61000-4-2 (ESD): Air 15kV, Contact 8kV
- ✓ 61000-4-4 (EFT): 40A 5/50ns
- ✓ 61000-4-5 (Surge): 12A, 8/20µs Level 1 (Line-Ground) & Level 2 (Line-Line)

### **FEATURES**

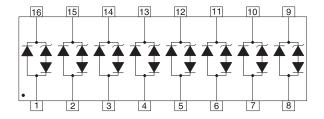
- ✓ 500 Watts Peak Pulse Power per Line (tp=8/20µs)
- ✓ Unidirectional & Bidirectional Configurations
- ✓ ESD Protection > 40 kilovolts
- ✔ Available in Multiple Voltage Types: 3.3V to 36V
- ✔ Protects up to Eight (8) Lines
- ✓ Low Capacitance: 15pF
- ✔ RoHS Compliant

#### **MECHANICAL CHARACTERISTICS**

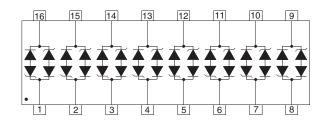
- ✓ Molded JEDEC SO-16 Package
- ✓ Weight 0.15 grams (Approximate)
- ✔ Available in Lead-Free Pure-Tin Plating(Annealed)
- ✓ Solder Reflow Temperature:
  - Pure-Tin Sn, 100: 260-270°C
- ✓ Flammability Rating UL 94V-0
- ✓ 16mm Tape and Reel per EIA Standard 481
- ✓ Marking: Logo, Part Number, Date Code & Pin One Defined By Dot on Top of Package

## PIN CONFIGURATIONS

UNIDIRECTIONAL CONFIGURATION



BIDIRECTIONAL CONFIGURATION





## DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified								
PARAMETER	SYMBOL	VALUE	UNITS					
Peak Pulse Power ( $t_p = 8/20\mu s$ ) - See Figure 1	P <sub>PP</sub>	500	Watts					
Operating Temperature	T <sub>L</sub>	-55 to 150	°C					
Storage Temperature	$T_{STG}$	-55 to 150	°C					
Forward Voltage @ 50mA, 300µs- Square Wave (Note 1)	V <sub>F</sub>	1.5	Volts					
Soldering Temperature for 10 seconds	T <sub>II</sub>	260	∞					

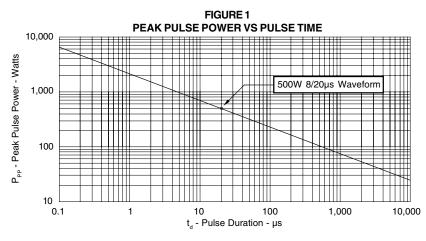
Note 1: Only applies to unidirectional devices.

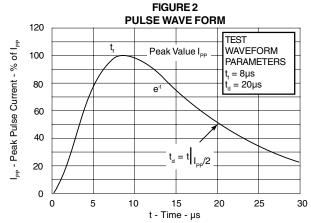
ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified										
PART NUMBER (See Note 1)	RATED STAND-OFF VOLTAGE	MINIMUM BREAKDOWN VOLTAGE	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM LEAKAGE CURRENT	MAXIMUM CAPACITANCE	TEMPERATURE COEFFICIENT OF V <sub>(BR)</sub>			
	V <sub>wm</sub> VOLTS	@ 1mA V <sub>(BR)</sub> VOLTS	@ I <sub>P</sub> = 1A V <sub>C</sub> VOLTS	@ 8/20µs V <sub>C</sub> @ I <sub>PP</sub>	@V <sub>wм</sub>	0V @ 1 MHz C pF	qV <sub>(BR)</sub> mV/°C			
SM16LC03 SM16LC03C SM16LC05 SM16LC05C SM16LC08C SM16LC12 SM16LC12C SM16LC15C SM16LC15C SM16LC24 SM16LC24C SM16LC24C SM16LC36 SM16LC36C	3.3 3.3 5.0 5.0 8.0 12.0 12.0 15.0 24.0 24.0 36.0 36.0	4.5 4.5 6.0 6.0 8.5 8.5 13.3 16.7 16.7 26.7 26.7 40.0	7.0 7.0 9.8 9.8 13.4 13.4 19.0 19.0 25.5 25.5 40.0 40.0 53.0 53.0	20.0V @ 35A 20.0V @ 35A 24.0V @ 42A 24.0V @ 42A 26.0V @ 30A 26.0V @ 30A 33.0V @ 21A 33.0V @ 21A 39.0V @ 15A 39.0V @ 15A 57.0V @ 10A 57.0V @ 10A 72.0V @ 7.0A	125 125 20 20 10 10 2 2 2 2 2 2	15 15 15 15 15 15 15 15 15 15	-3 -3 3 9 9 16 16 17 17 26 26 36 36			

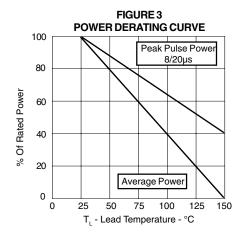
**Note 1:** Part numbers with a "C" suffix are bidirectional devices, i.e., SM16LC05<u>C</u>.

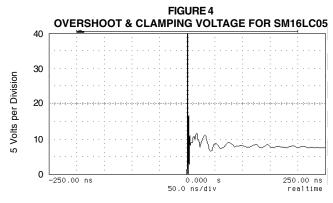
## SM16LC03 thru SM16LC36C

## GRAPHS

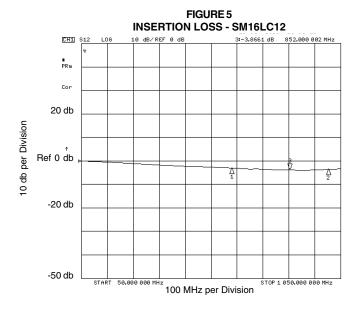


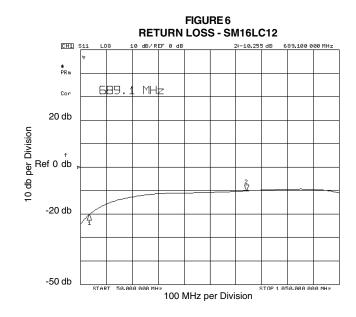






ESD Test Pulse: 25 kilovolt, 1/30ns (waveform)





## SM16LC03 thru SM16LC36C

## APPLICATION NOTE

The SM16LC & SM16LCxxC Series are TVS arrays designed to protect I/O or data lines from the damaging effects of ESD, EFT and other types of surges. This product series provides both unidiretional and bidirectional protection, with a surge capability of 500 Watts  $P_{pp}$  per line for an 8/20 $\mu$ s waveform and ESD protection > 40kV.

### **BIDIRECTIONAL COMMON-MODE CONFIGURATION (Figure 1)**

Ideal for RS-485 applications, the SM16LCxxC Series provides up to eight (8) lines of protection in a common-mode configuration as depicted in Figure 1. This low capacitance series allows the transceiver or telecommunications circuit to operate safely without significant signal distortion.

Circuit connectivity is as follows:

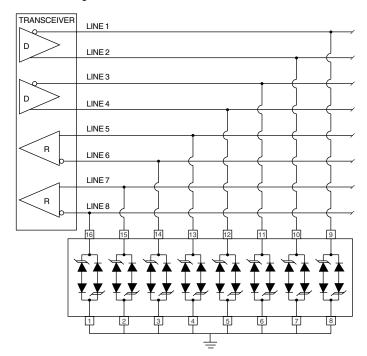
- ✓ Lines 1 is connected to Pin 9.
- ✓ Line 2 is connected to Pin 10.
- ✓ Line 3 is connected to Pin 11.
- ✓ Line 4 is connected to Pin 12.
- ✓ Line 5 is connected to Pin 13.
- ✓ Line 6 is connected to Pin 14.
- ✓ Line 7 is connected to Pin 15.
- ✓ Line 8 is connected to Pin 16.
- Pins 1-8 are connected to ground.

#### CIRCUIT BOARD LAYOUT RECOMMENDATIONS

Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

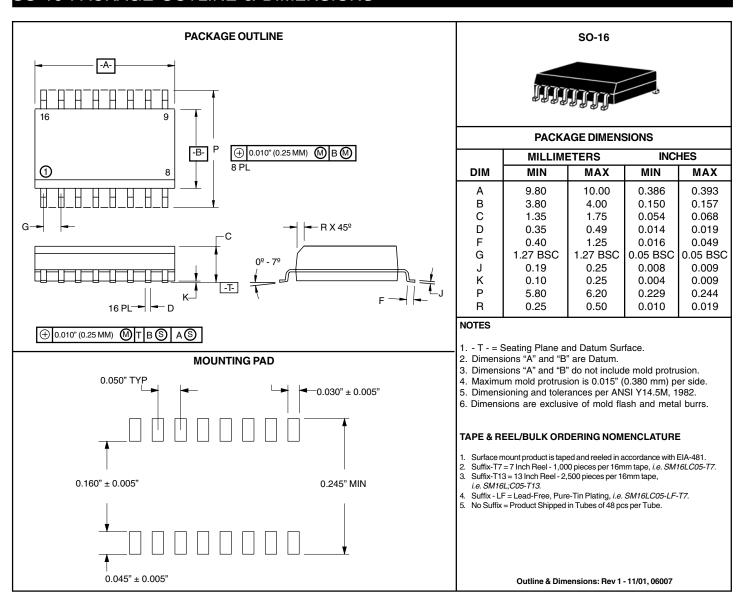
- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

Figure 1. Birectional Common-Mode Protection



## **SM16LC03** SM16LC36C

## SO-16 PACKAGE OUTLINE & DIMENSIONS



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